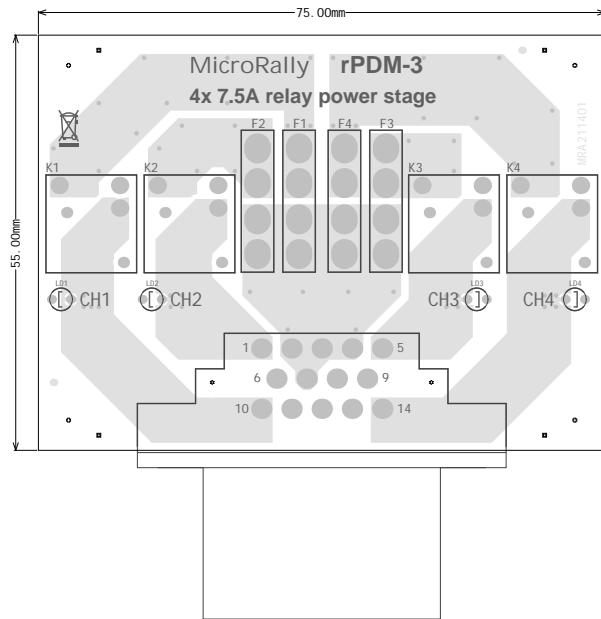
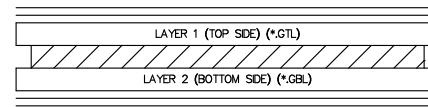


# GERBER NOTES



Symbol	Count	Hole Size	Plated	Hole Type	Via/Pad
◇	51	0.300mm	PTH	Round	Via
⊗	8	0.750mm	PTH	Round	Pad
○	8	0.800mm	PTH	Round	Pad
■	4	1.152mm	NPTH	Round	Pad
□	12	1.300mm	PTH	Round	Pad
⊗	14	1.600mm	PTH	Round	Pad
▽	16	2.500mm	PTH	Round	Pad
☆	2	2.850mm	NPTH	Round	Pad
⊕	4	3.200mm	NPTH	Round	Pad
	119 Total				

1.0 OZ L1  
1.50 mm Core - FR4  
1.0 OZ L2



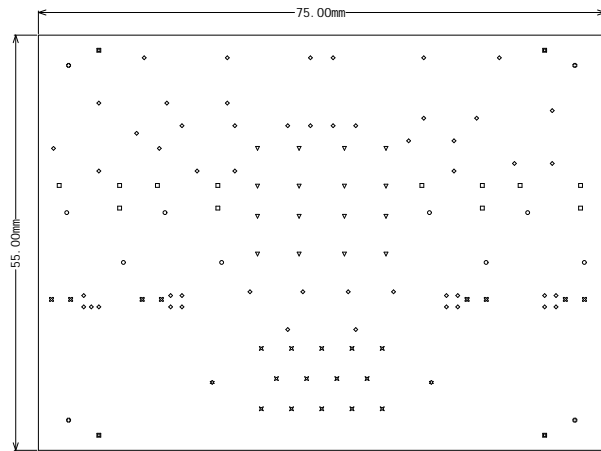
SILKSCREEN (TOP SIDE) (\*GTO)  
SOLDERMASK (TOP SIDE) (\*GTS)  
1.6 mm +/- 10% LAYER DETAIL  
2 LAYERS  
SOLDERMASK (BOTTOM SIDE) (\*G2S)  
SILKSCREEN (BOTTOM SIDE) (\*G2B)  
PASTE (BOTTOM SIDE) (\*G2P)

## NOTES: (UNLESS OTHERWISE SPECIFIED)

- THIS IS 2 LAYER BOARD
- MATERIAL: FR4, TG 150 DEGREE C MIN
- FR4 DIELECTRIC CONSTANT NOT SPECIFIED
- FINISHED BOARD THICKNESS TO BE 1.60MM +/- 10%
- TRACE WIDTHS IN ARTWORK ARE FINISHED SIZES
- SEE FILM FOR LAYER SEQUENCE AND COPPER THICKNESSES (SHOWN BEFORE PLATING)
- MIN TRACE/SPACE 0.60/0.25MM
- SEE DRILL CHART FOR FINISHED HOLE SIZES
- MIN DRILL 0.75MM
- HOLE TOLERANCE IS +/-3MIL UNLESS OTHERWISE SPECIFIED  
HOLE COPPER THICKNESS MIN 0.7MIL  
SLOT TOLERANCE +/-0.1MM  
BORDER OUTLINE TOLERANCE +/-0.15MM
- SURFACE PLATING: HASL, Pb FREE
- SOLDERMASK: LPI, BOTH SIDES. COLOR GREEN
- SILKSCREEN: TOP AND BOTTOM SIDE. COLOR WHITE
- ALL BOARDS MUST BE ELECTRICALLY TESTED FOR ISOLATION (SHORTS) AND CONTINUITY (OPENS)

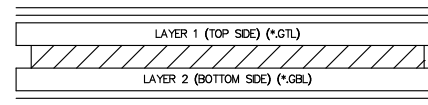
Project: rPDM-3	
Author: Andis Jargans	Revision: 1
Date: 08.04.2021	Size: A4
File: rPDM-3_r1.PcbDoc	MicroRally

# GERBER NOTES



Symbol	Count	Hole Size	Plated	Hole Type	Via/Pad
◇	51	0.300mm	PTH	Round	Via
⊗	8	0.750mm	PTH	Round	Pad
○	8	0.800mm	PTH	Round	Pad
■	4	1.152mm	NPTH	Round	Pad
□	12	1.300mm	PTH	Round	Pad
⊗	14	1.600mm	PTH	Round	Pad
▽	16	2.500mm	PTH	Round	Pad
☆	2	2.850mm	NPTH	Round	Pad
⊕	4	3.200mm	NPTH	Round	Pad
	119 Total				

1.0 OZ L1  
 1.50 mm Core - FR4  
 1.0 OZ L2



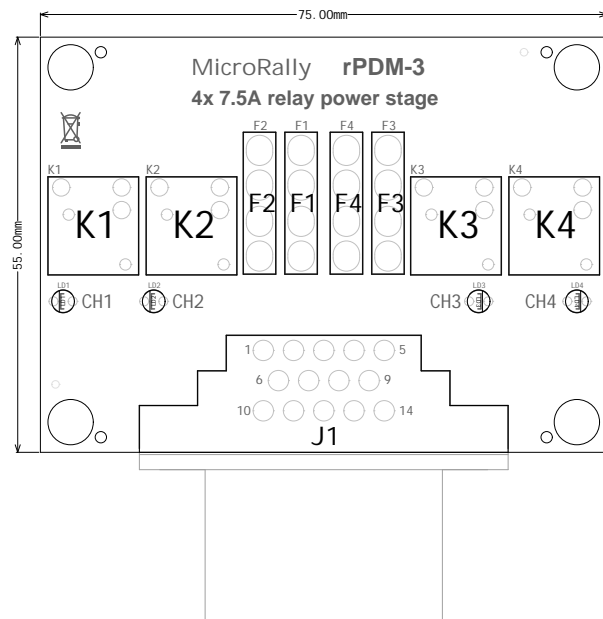
↑ SILKSCREEN (TOP SIDE) (\*GTO)  
 SOLDERMASK (TOP SIDE) (\*GTS)  
 1.6 mm +/- 10% LAYER DETAIL  
 2 LAYERS  
 ↓ SOLDERMASK (BOTTOM SIDE) (\*GBS)  
 SILKSCREEN (BOTTOM SIDE) (\*GB0)  
 PASTE (BOTTOM SIDE) (\*GBP)

## NOTES: (UNLESS OTHERWISE SPECIFIED)

- THIS IS 2 LAYER BOARD
- MATERIAL: FR4, TG 150 DEGREE C MIN
- FR4 DIELECTRIC CONSTANT NOT SPECIFIED
- FINISHED BOARD THICKNESS TO BE 1.60MM +/- 10%
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- SOLDERMASK: LPI, BOTH SIDES. COLOR GREEN
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- ALL BOARDS MUST BE ELECTRICALLY TESTED FOR ISOLATION (SHORTS) AND CONTINUITY (OPENS)

Project: rPDM-3	
Author: Andis Jargans	Revision: 1
Date: 08.04.2021	Size: A4
File: rPDM-3_r1.PcbDoc	Microwally

# ASSEMBLY NOTES



Project: rPDM-3	
Author: Andi s Jargans	Revisi on: 1
Date: 08.04.2021	Size: A4
File: rPDM-3_r1.PcbDoc	MicroRally

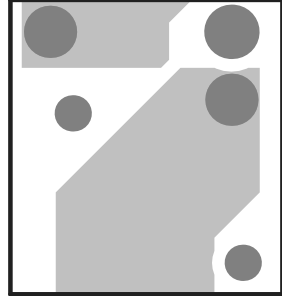
# MicroRally rPDM-3

## 4x 7.5A relay power stage

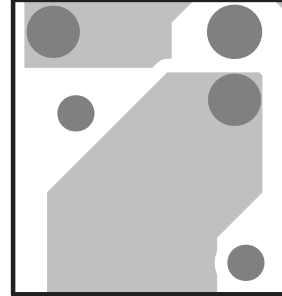
MRA211401



K1



K2



F2



F1



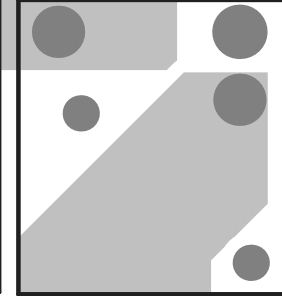
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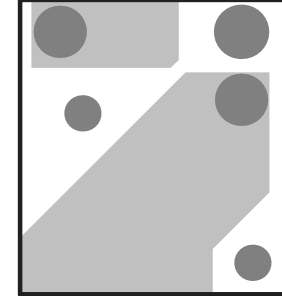
F3



K3



K4



LD1



CH1

LD2



CH2

LD3



CH3

LD4



CH4

1



5



6



9



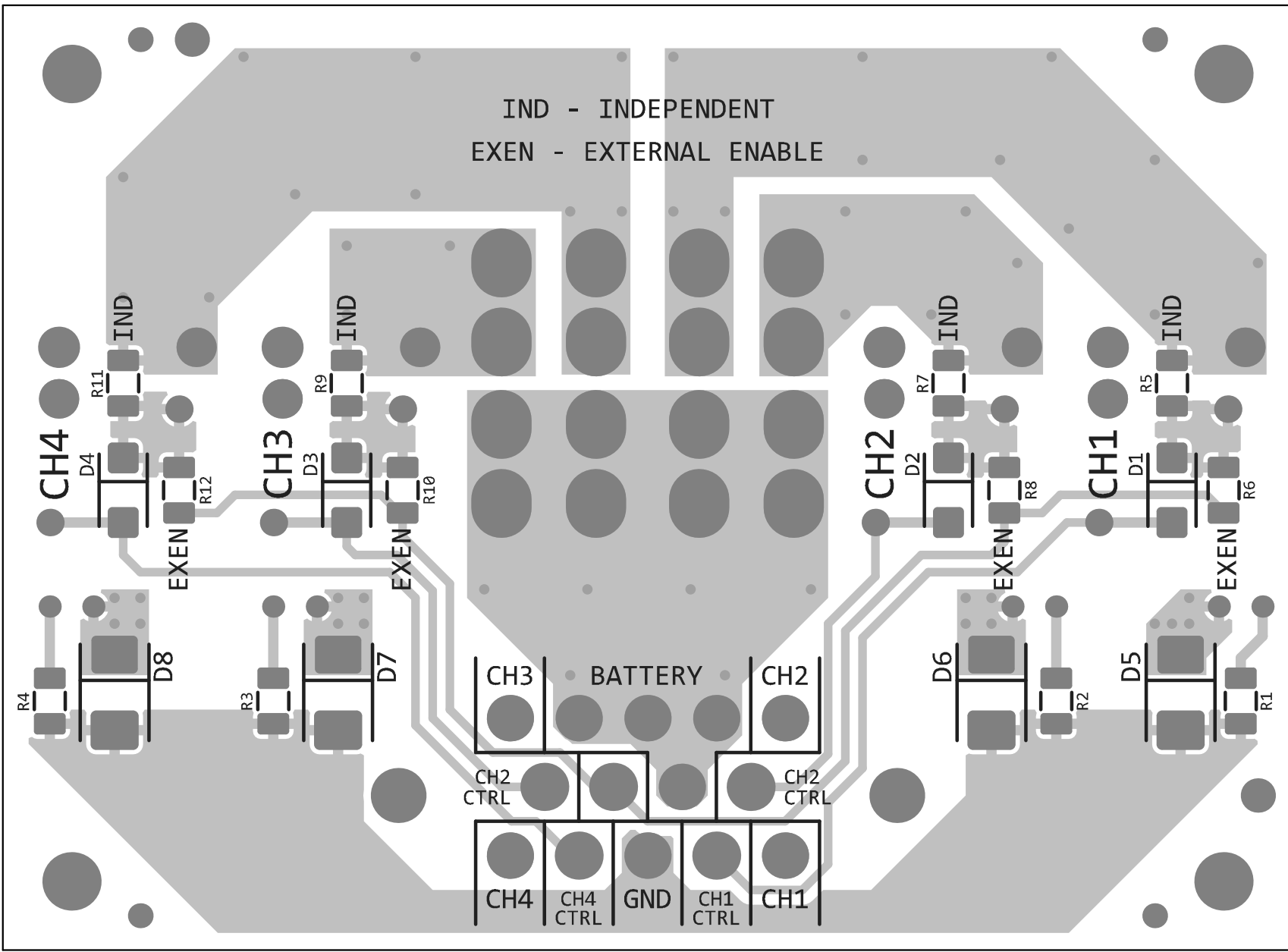
10



14



IND - INDEPENDENT  
EXEN - EXTERNAL ENABLE



R4

CH4

D4

R11

IND

EXEN

R12

R3

D7

CH3

D3

R9

IND

EXEN

R10

CH3

BATTERY

CH2

CH2 CTRL

CH2 CTRL

CH4

CH4 CTRL

GND

CH1 CTRL

CH1

D6

CH2

D2

R7

IND

EXEN

R8

R2

D5

CH1

D1

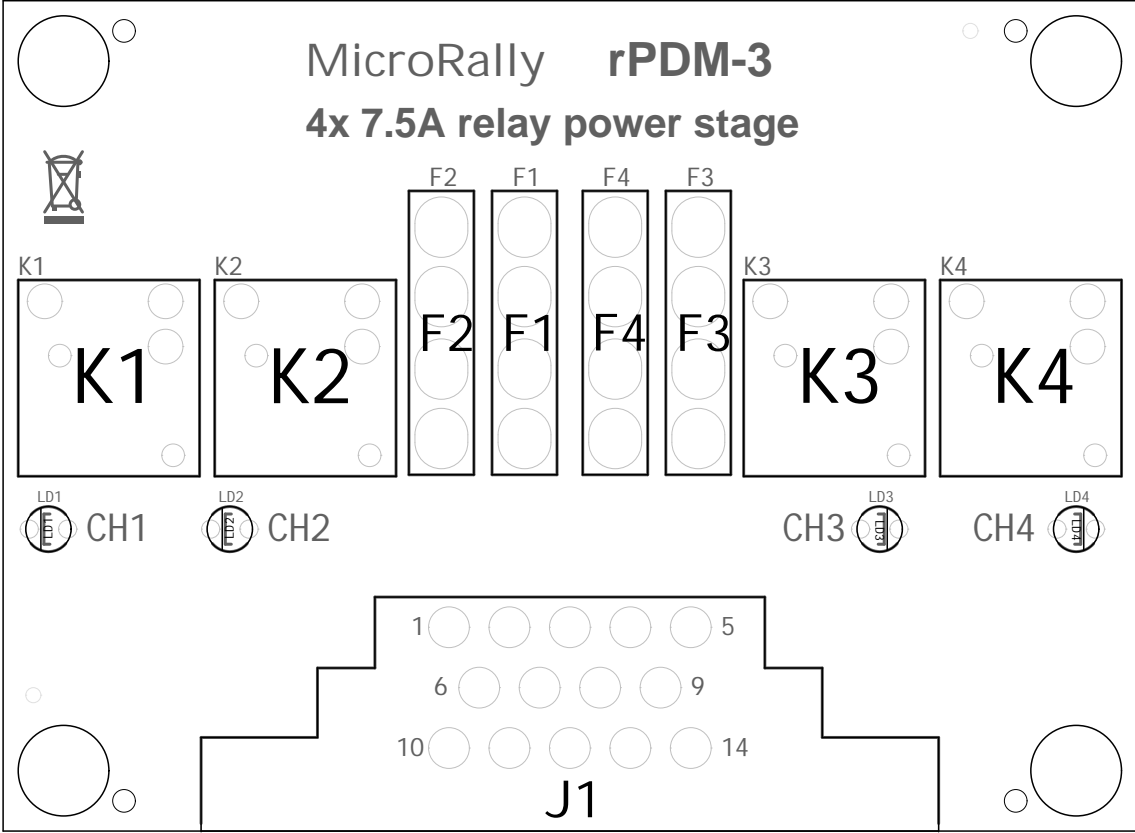
R5

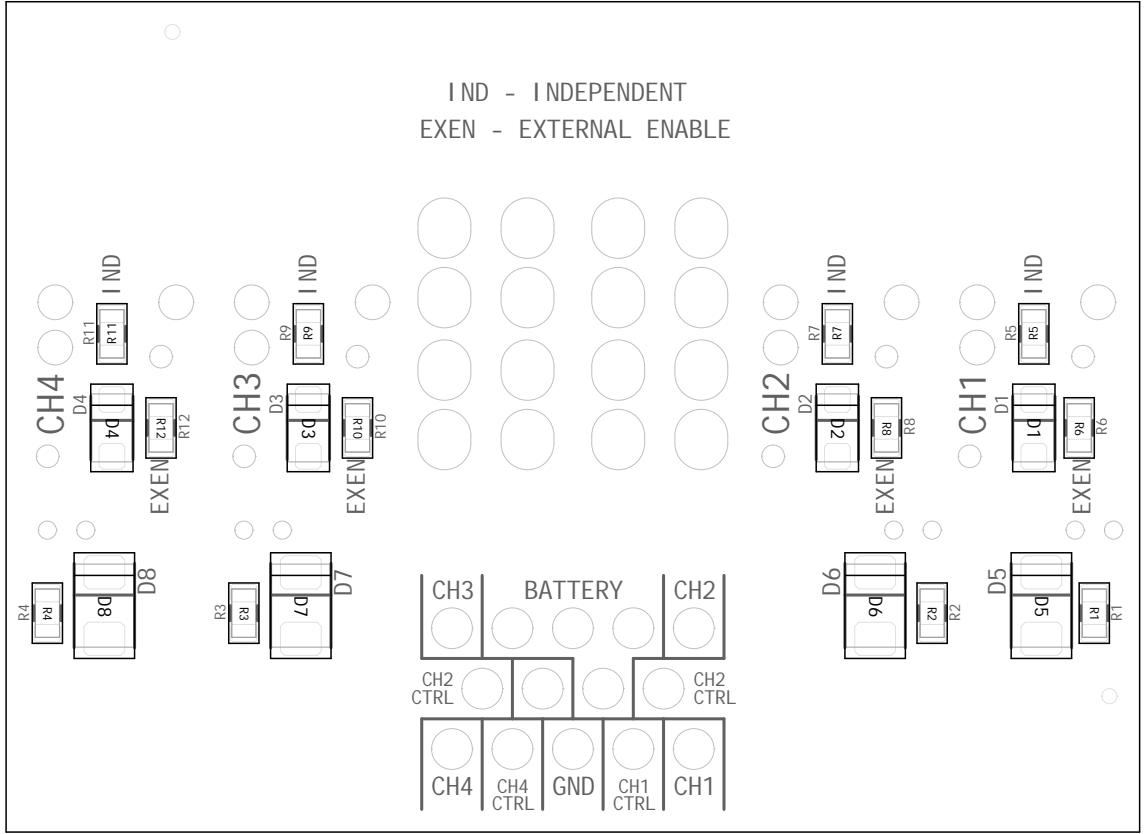
IND

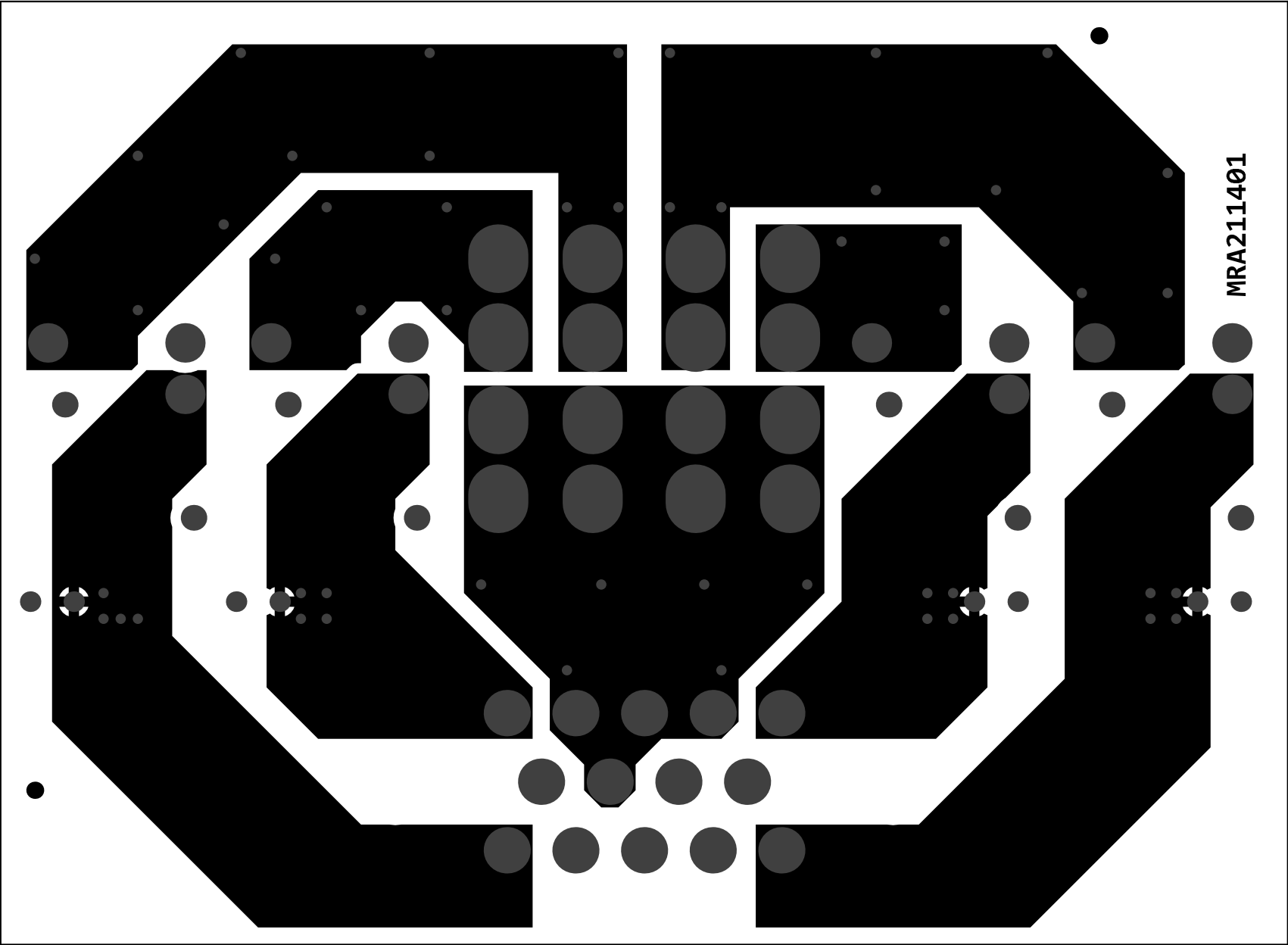
EXEN

R6

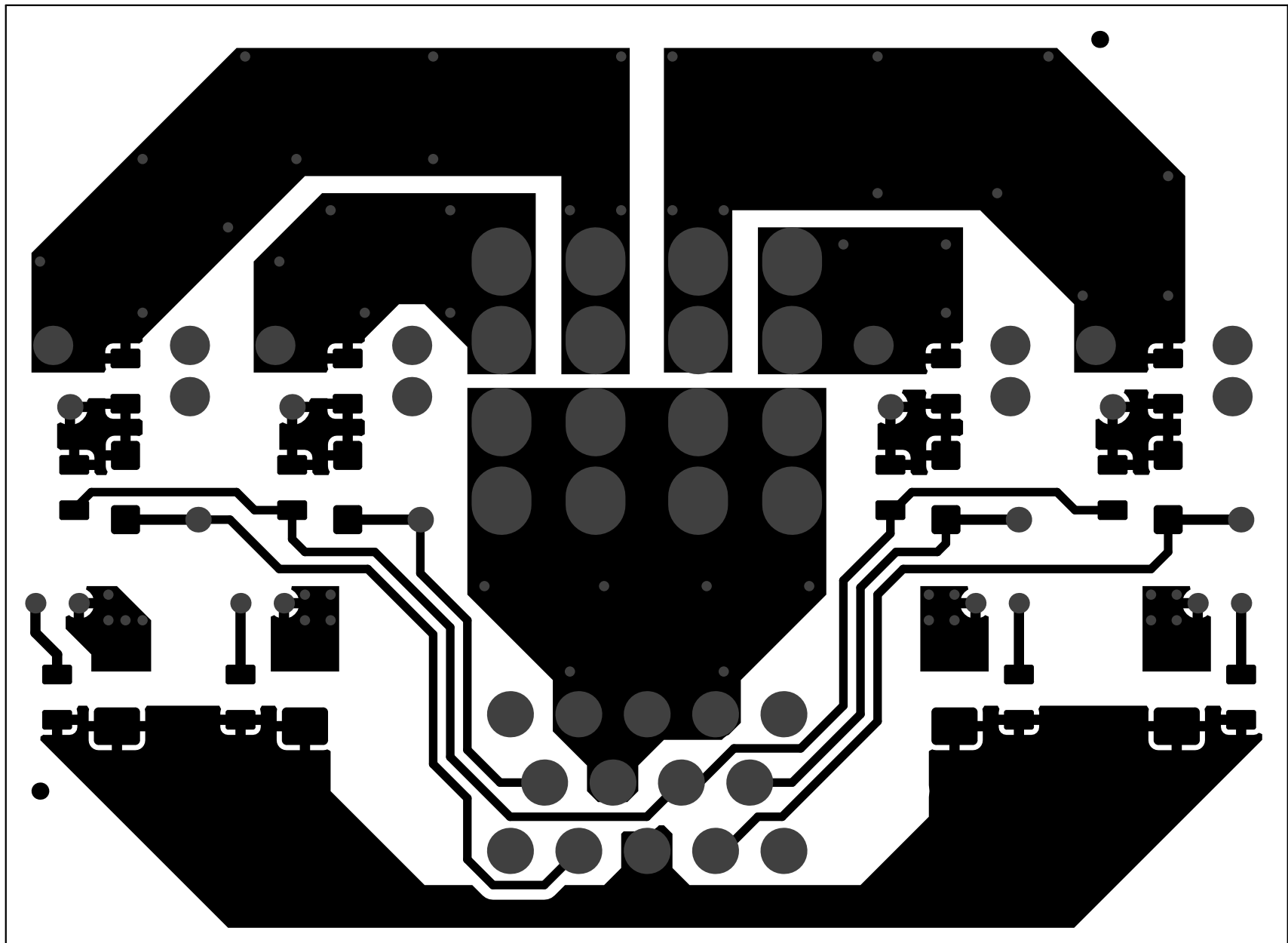
R1







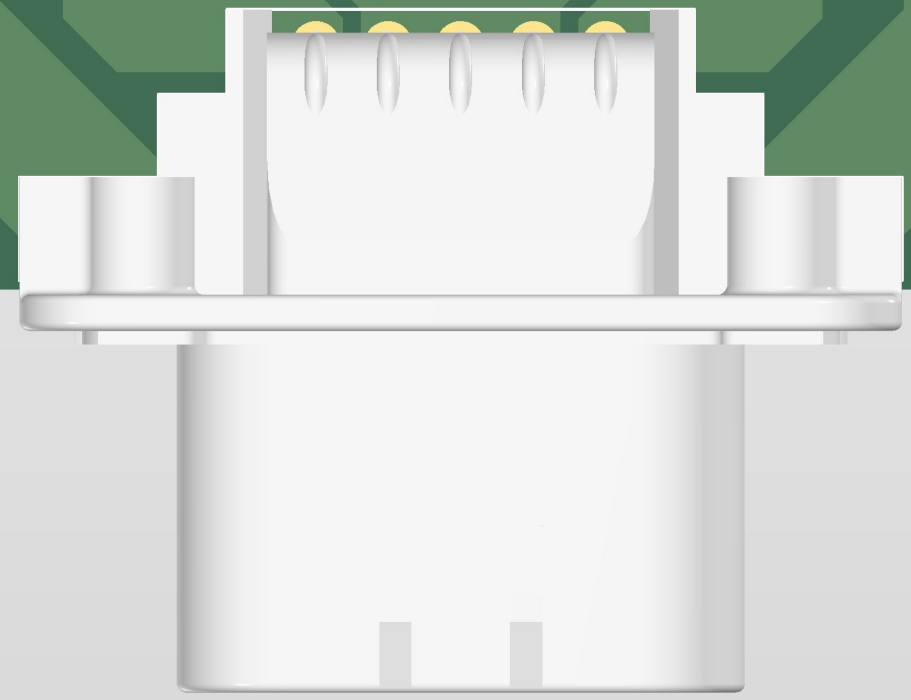
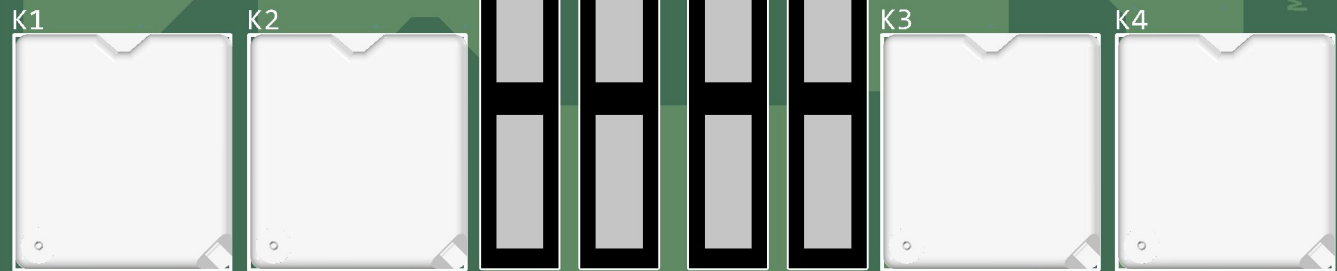
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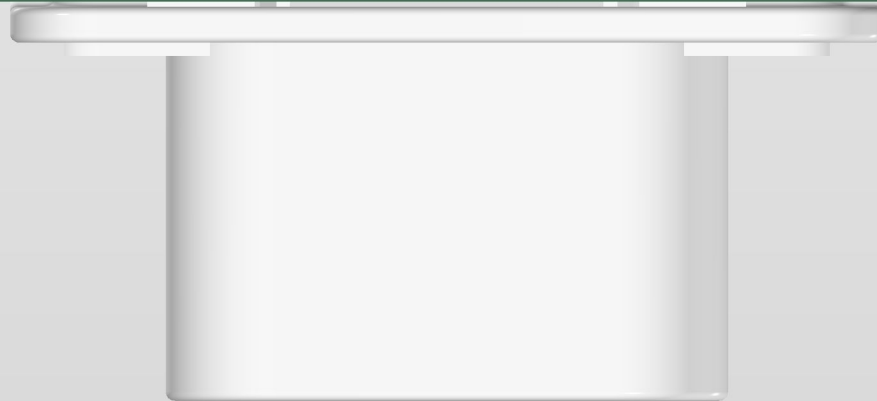
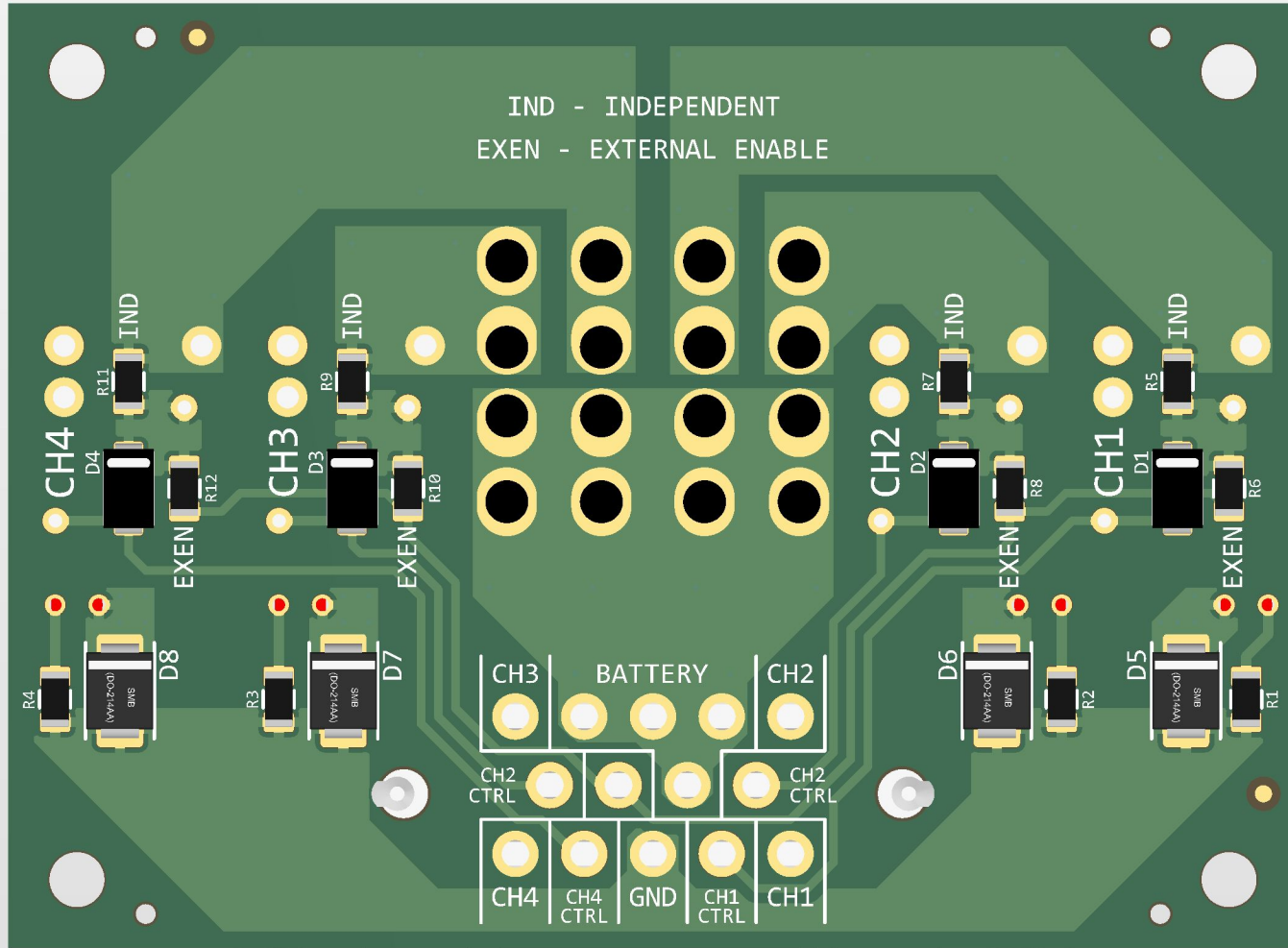


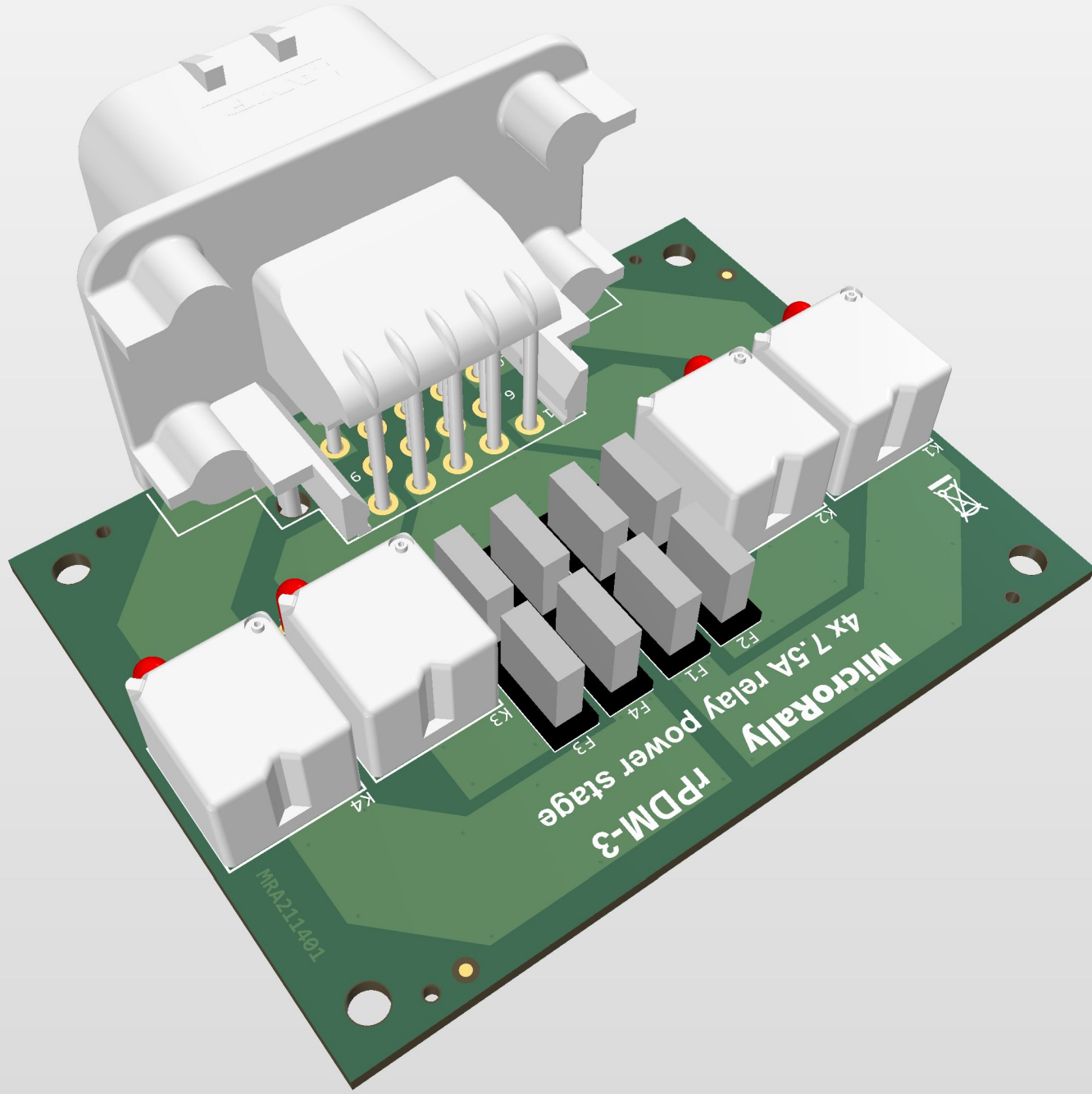
# MicroRally rPDM-3

## 4x 7.5A relay power stage

MRA211401







MicroRally

rPDM-3

4x 7.5A relay power stage

MRA211401

K4

F4

F3

F1

F2

K2

K1

9

8

7

6

5

4

3

2

1

